Silicon N-Channel Power MOS FET Module

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Application

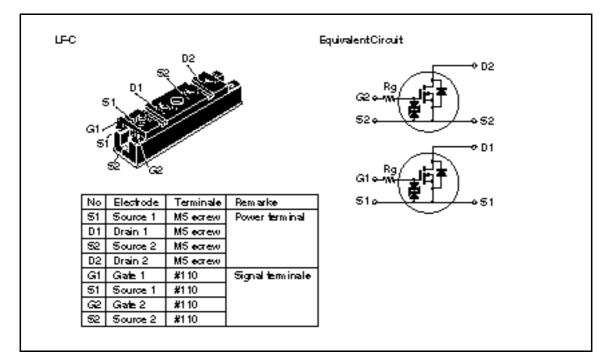
High Speed Power Switching

Features

- Equipped with Power MOS FET
- Low on-resistance
- High speed switching
- Low drive current
- Wide area of safe operation
- Inherent parallel diode between source and drain
- Isolated base from Terminal
- Suitable for motor driver, switching regulator and etc.



Outline



Absolute Maximum Ratings (Ta = 25°C) (Per FET chip)

Item	Symbol	Rating	Unit	
Drain source voltage	V _{DSS}	450	V	
Gate source voltage	V _{GSS}	±20	V	
Drain current	I _D	50	А	
Drain peak current	I _{D(peak)}	100	А	
Body to drain diode reverse drain current	I _{DR}	50	А	
Body to drain diode reverse drain peak current	DR(peak)	100	А	
Channel dissipation	Pch*1	300	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-45 to +125	°C	
Insulation dielectric	Visol*2	2000	V	

Notes: 1. Value at Tc = 25°C

2. Base to terminals AC minute

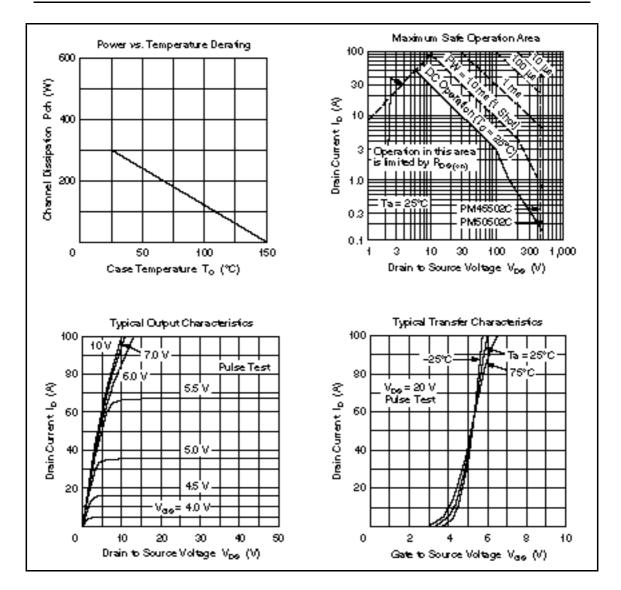
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	450	_	_	V	$I_{\rm D} = 10$ mA, $V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±50	μA	$V_{GS} = \pm 16 V, V_{DS} = 0$
Gate to source breakdown voltage	$V_{\rm (BR)GSS}$	±20	—	_	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	_	1	mA	$V_{DS} = 360 \text{ V}, V_{GS} = 0$
Gate to source threshold voltage	$V_{\text{GS(th)}}$	1.5	_	4.0	V	$I_{\rm D} = 1$ mA, $V_{\rm DS} = 10$ V
Drain to source saturation voltage	$V_{\text{DS(on)}}$	_	2.0	3.0	V	$I_{\rm D} = 25$ A, $V_{\rm GS} = 10$ V* ¹
Static Drain to source on state resistance	$R_{\text{DS(on)}}$	—	0.08	0.12		$I_{\rm D} = 25$ A, $V_{\rm GS} = 10$ V* ¹
Forward transfer admittance	y _{fs}	25	40	—	S	$I_{\rm D} = 25$ A, $V_{\rm DS} = 10$ V ^{*1}
Input capacitance	Ciss	_	10250	_	рF	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0$
Output capacitance	Coss	_	3600	_	рF	f = 1 MHz
Reverse transfer capacitance	Crss	—	400	—	pF	_
Turn-on delay time	t _{d(on)}	_	150	_	ns	$I_{\rm D} = 25$ A, $V_{\rm GS} = 10$ V
Rise time	t,	_	700	_	ns	
Turn-off delay time	$t_{d(off)}$	—	800	—	ns	_
Fall time	t _f	_	600	_	ns	-
Body to drain diode forward voltage	V_{DF}	—	1.2	—	V	$I_{\rm F} = 25$ A, $V_{\rm GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		200	_	ns	I _F = 25 A, V _{GS} = 0 diF/dt = 100 A/μs

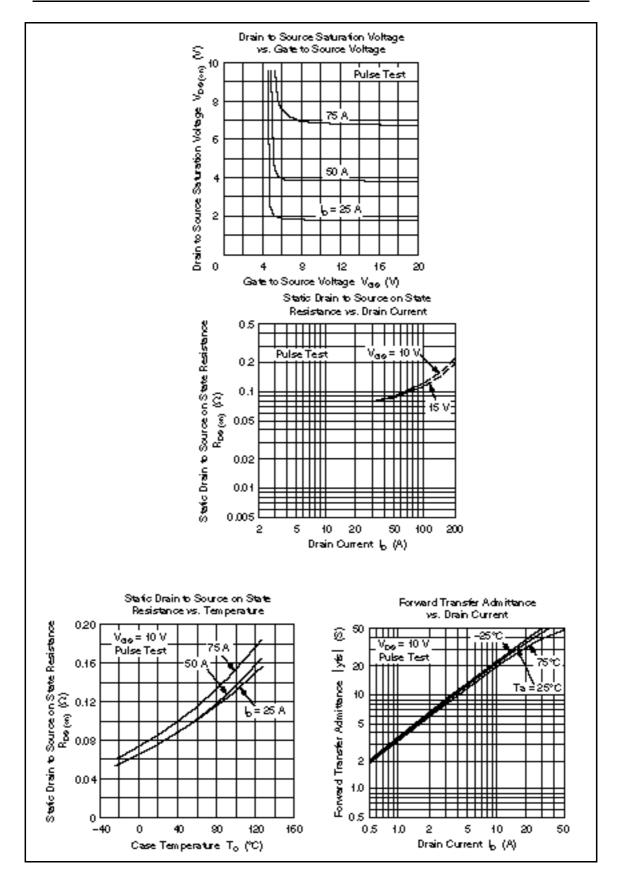
Electrical Characteristics (Ta = 25°C) (Per FET chip)

Note: 1. Pulse Test

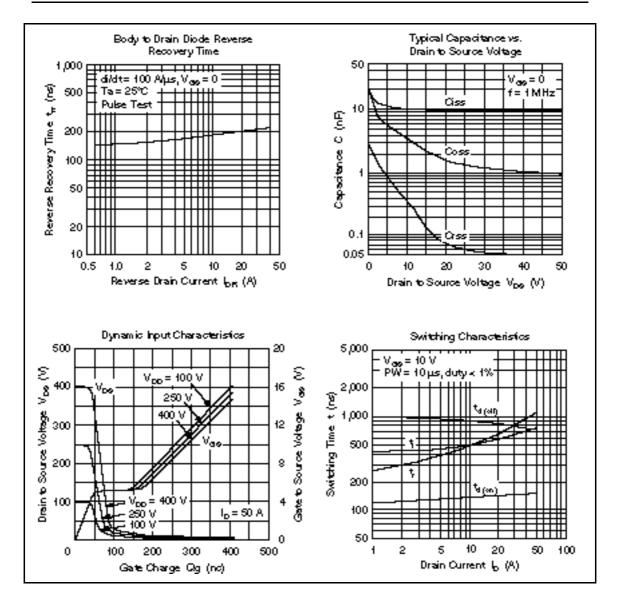
Mechanical Characteristics

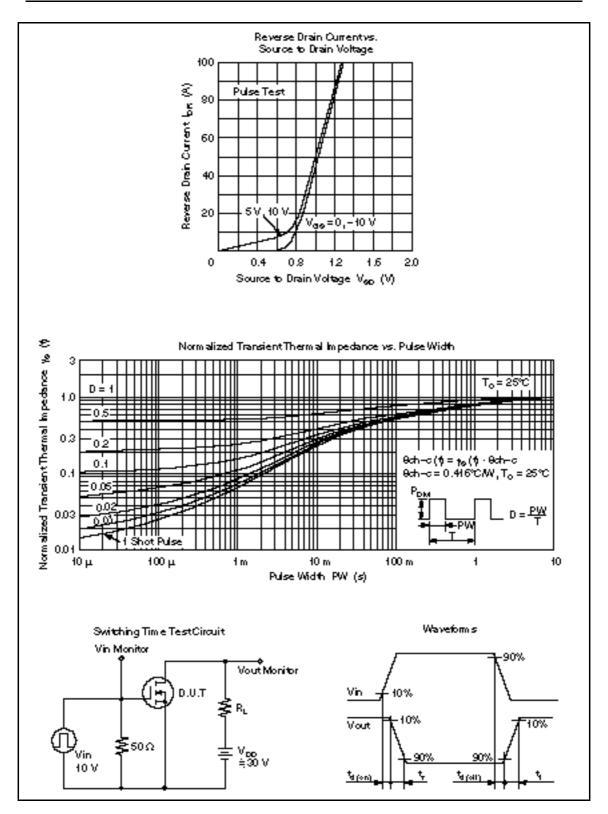
Item	Symbol	Condition	Rating	Unit
Fixing strength	_	Mounting into main-terminal with M5 screw	15 to 20	kg∙cm
	_	Mounting into heat sink with M6 screw	20 to 30	kg∙cm
Weight	_	Typical value	300	g





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